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N THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Grant Kenji Larsen

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Confirmation No:

2719

Filed:

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For:

SURFACE STRUCUTRE AND METHOD OF MAKING, AND

ELECTROSTATIC WAFER CLAMP INCORPORATING

SURFACE STRUCTURE

Examiner:

Stephen W. Jackson

Art Unit:

2836

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

The undersigned hereby certifies that this document is being placed in the United States mail with first-class postage attached, addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the Oday of June, 2003.

Cheryl Rurcell

Commissioner for Patents

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Sir:

Transmitted herewith are the following documents:

[X] Response Under 37 CFR § 1.111

[X] Petition for Extension of Time

[X] Terminal Disclaimer

[X] Return Receipt Postcard

If any additional fees are determined to be required or if there are any overpayments,

Deposit Account 50-0896 may be charged or credited. A duplicate of this sheet is enclosed.

Respectfully submitted,

Grant Kenji Larsen, Applicant

By:

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Docket No. VSEA 16-99

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